

Plating Capabilities

Plated Materials Offered:

- Copper
- Nickel
- Gold
- Silver
- Tin
- Tin/Lead

Plating Process:

CONFIGURATION	SIZE CAPABILITY
Round wire:	.0008" (.020mm) to 0.025" (0.635mm)
Flat wire:	.001" - (.025mm) minimum thickness
Square wire:	(.010" × .010") - (.25mm × .25mm)
Other - call with requirements	
PLATING TYPE	THICKNESS
Under plate (Flash):	5-15 micro inches - (.000005"-0.000015")
Primary plating:	20 micro inches (0.00002") to 400 micro inches (0.0004")
Other - call with requirements	

Base Materials:

- Aluminum and alloys
- Beryllium Copper
- Copper and alloys
- Dumet[®] Carpenter Technology
- Elgiloy[®] Elgiloy Inc.
- Kovar[®] Carpenter Technology
- Molybdenum
- Monel[®] Inco Family of Products
- Nickel and alloys
- Precious Metals – Platinum, Silver, Platinum Iridium
- Resistance alloys – Stablohm, Manganin, Ni-Cu alloys, Ni-Fe alloys, etc.
- Stainless Steel
- Titanium
- Tungsten
- And many more**

Applications and Industries Served:

APPLICATIONS	INDUSTRIES SERVED
Connector pins	Aerospace Industry
Drift chamber/Particle detection wire	Automotive Industry
Fuse wire	Chemical Industry
Hearing-aids	Computer Industry
Lead wire/ribbons	Electronics Industry
Microphones	Measurement Device Manufactures
Sensors	Medical Industry
Speakers	Microwave Industry
Springs	Particle Research
Transducers	Research Laboratories
	Spring Manufactures